

Glass Core Substrate Market Forecasts to 2034 – Global Analysis By Glass Type (Borosilicate Glass, Fused Silica Glass, Aluminosilicate Glass, Quartz Glass, and Other Specialty Glasses), Substrate Size, Manufacturing Process, Application, End User and By Geography

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Abstracts

According to Statistics MRC, the Global Glass Core Substrate Market is accounted for \$0.3 billion in 2026 and is expected to reach \$4.7 billion by 2034, growing at a CAGR of 41.0% during the forecast period. Glass core substrates refer to advanced packaging substrates fabricated using glass as the base material, offering superior electrical, thermal, and mechanical properties compared to traditional organic substrates. These substrates enable higher interconnect density, improved signal integrity, and better thermal management for demanding semiconductor applications. As a result, glass core substrates have emerged as a critical enabling technology for advanced semiconductor packaging.

Market Dynamics:

Driver:

Growing demand for advanced packaging and heterogeneous integration

The increasing demand for advanced packaging solutions and heterogeneous integration serves as a primary catalyst for the glass core substrate market. As semiconductor technology scaling becomes more challenging, advanced packaging approaches including 2.5D and 3D integration enable continued performance

improvements. Glass core substrates offer superior electrical performance, lower signal loss, and better thermal management compared to organic substrates, making them ideal for demanding applications. The need for higher interconnect density and improved signal integrity in AI processors, HPC systems, and data centers drives adoption. As semiconductor packaging complexity increases, the demand for glass core substrate solutions continues to grow.

Restraint:

Higher costs and manufacturing complexity

The glass core substrate market faces significant challenges from higher costs and manufacturing complexity compared to traditional organic substrate solutions. Glass substrate fabrication requires specialized manufacturing processes including glass handling, via formation, and metallization, which are more complex and costly than organic substrate production. The brittleness of glass requires careful handling throughout the manufacturing process. Additionally, the development of reliable through-glass via technology and high-yield manufacturing processes requires substantial investment. These cost and complexity factors can limit adoption in cost-sensitive applications and create barriers to widespread implementation.

Opportunity:

Growth of AI and high-performance computing applications

The rapid expansion of AI and high-performance computing applications presents significant opportunities for glass core substrate providers. AI processors and HPC systems require advanced packaging solutions capable of delivering high bandwidth, low latency, and excellent signal integrity. Glass core substrates offer the electrical and thermal performance necessary for demanding computing applications. The increasing use of chiplet-based architectures and heterogeneous integration creates demand for advanced substrates that can support complex interconnect schemes. As computing requirements continue to grow, the demand for glass core substrates in high-performance applications continues to expand.

Threat:

Competition from organic substrates and emerging alternatives

The glass core substrate market faces threats from competition from organic substrates and emerging alternative technologies that could limit adoption. Organic substrates continue to improve in performance, narrowing the gap with glass in some applications. Additionally, emerging substrate technologies including silicon interposers and advanced organic solutions compete for advanced packaging applications. The development of new substrate materials and manufacturing approaches could provide alternatives to glass cores. These competitive pressures require glass core substrate providers to demonstrate clear performance advantages and pursue cost reduction.

Covid-19 Impact:

The COVID-19 pandemic significantly impacted the glass core substrate market by accelerating demand for advanced packaging solutions in AI and computing applications while disrupting supply chains and manufacturing operations. The shift toward remote work and digital services increased demand for data center infrastructure and AI computing, driving interest in advanced packaging technologies. Supply chain disruptions affected specialized materials and component availability. The semiconductor industry's focus on advanced packaging for performance scaling continued despite pandemic challenges. As semiconductor demand recovered and advanced packaging investments increased, the focus on glass core substrates for high-performance applications intensified.

The borosilicate glass segment is expected to be the largest during the forecast period

The borosilicate glass segment is expected to account for the largest market share during the forecast period, driven by its favorable properties including low thermal expansion coefficient, high chemical durability, and excellent electrical properties that make it well-suited for substrate applications. Borosilicate glass offers good dimensional stability and compatibility with semiconductor manufacturing processes. As the most mature glass type for substrate applications, borosilicate glass maintains the largest market share across various end-use applications.

The through-glass via segment is expected to have the highest CAGR during the forecast period

Over the forecast period, the through-glass via segment is predicted to witness the highest growth rate, driven by the increasing importance of TGV technology for enabling high-density interconnects, improved signal integrity, and efficient thermal management in glass core substrates for advanced packaging applications. Through-glass via

enables vertical electrical connections through the glass substrate, supporting 2.5D and 3D integration approaches. As advanced packaging requirements become more demanding, the adoption of TGV technology in glass core substrates continues to accelerate.

Region with largest share:

During the forecast period, the Asia Pacific region is expected to hold the largest market share, driven by the presence of leading semiconductor packaging companies, strong substrate manufacturing capabilities, significant investment in advanced packaging technologies, and concentration of electronics manufacturing across countries like Taiwan, South Korea, Japan, China, and Singapore. The region's dominance in semiconductor packaging and substrate manufacturing supports market leadership. Additionally, the concentration of electronics manufacturing and semiconductor packaging contributes to the region's largest market share.

Region with highest CAGR:

Over the forecast period, the Asia Pacific region is also anticipated to exhibit the highest CAGR, reinforcing its market leadership through continued investment in advanced packaging capabilities and semiconductor manufacturing expansion. The growth is fueled by increasing adoption of glass core substrates in AI, HPC, and data center applications across Asia Pacific countries. The rapid expansion of advanced packaging capacity and increasing focus on high-performance computing applications across the region accelerates glass core substrate adoption at the fastest pace.

Key players in the market

Some of the key players in Glass Core Substrate Market include Corning Incorporated, AGC Inc., Schott AG, Samsung Electro-Mechanics Co. Ltd., Absolics Inc., LG Innotek Co. Ltd., Intel Corporation, Ibiden Co. Ltd., Shinko Electric Industries Co. Ltd., TOPPAN Holdings Inc., Kyocera Corporation, Unimicron Technology Corporation, Nan Ya Printed Circuit Board Corporation, Kinsus Interconnect Technology Corp., and Daeduck Electronics Co. Ltd.

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In March 2025, Corning Incorporated announced its latest glass core substrate product featuring advanced through-glass via technology for AI and HPC applications. The

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In February 2025, Samsung Electro-Mechanics unveiled its next-generation glass core substrate platform for advanced semiconductor packaging. The platform supports high-density interconnects and improved electrical performance for AI processors and memory devices.

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Belgium

Sweden

Switzerland

Poland

Rest of Europe

Asia Pacific

China

Japan

India

South Korea

Australia

Indonesia

Thailand

Malaysia

Singapore

Vietnam

Rest of Asia Pacific

South America

Brazil

Argentina

Colombia

Chile

Peru

Rest of South America

Rest of the World (RoW)

Middle East

Saudi Arabia

United Arab Emirates

Qatar

Israel

Rest of Middle East

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Benchmarking of key players based on product portfolio, geographical presence, and strategic alliances

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Belgium

Sweden

Switzerland

Poland

Rest of Europe

Asia Pacific

China

Japan

India

South Korea

Australia

Indonesia

Thailand

Malaysia

Singapore

Vietnam

Rest of Asia Pacific

South America

Brazil

Argentina

Colombia

Chile

Peru

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Competitive Benchmarking

Benchmarking of key players based on product portfolio, geographical presence, and strategic alliances

Contents

1 EXECUTIVE SUMMARY

- 1.1 Market Snapshot and Key Highlights
- 1.2 Growth Drivers, Challenges, and Opportunities
- 1.3 Competitive Landscape Overview
- 1.4 Strategic Insights and Recommendations

2 RESEARCH FRAMEWORK

- 2.1 Study Objectives and Scope
- 2.2 Stakeholder Analysis
- 2.3 Research Assumptions and Limitations
- 2.4 Research Methodology
 - 2.4.1 Data Collection (Primary and Secondary)
 - 2.4.2 Data Modeling and Estimation Techniques
 - 2.4.3 Data Validation and Triangulation
 - 2.4.4 Analytical and Forecasting Approach

3 MARKET DYNAMICS AND TREND ANALYSIS

- 3.1 Market Definition and Structure
- 3.2 Key Market Drivers
- 3.3 Market Restraints and Challenges
- 3.4 Growth Opportunities and Investment Hotspots
- 3.5 Industry Threats and Risk Assessment
- 3.6 Technology and Innovation Landscape
- 3.7 Emerging and High-Growth Markets
- 3.8 Regulatory and Policy Environment
- 3.9 Impact of COVID-19 and Recovery Outlook

4 COMPETITIVE AND STRATEGIC ASSESSMENT

- 4.1 Porter's Five Forces Analysis
 - 4.1.1 Supplier Bargaining Power
 - 4.1.2 Buyer Bargaining Power
 - 4.1.3 Threat of Substitutes
 - 4.1.4 Threat of New Entrants

- 4.1.5 Competitive Rivalry
- 4.2 Market Share Analysis of Key Players
- 4.3 Product Benchmarking and Performance Comparison

5 GLOBAL GLASS CORE SUBSTRATE MARKET, BY GLASS TYPE

- 5.1 Borosilicate Glass
- 5.2 Fused Silica Glass
- 5.3 Aluminosilicate Glass
- 5.4 Quartz Glass
- 5.5 Other Specialty Glasses

6 GLOBAL GLASS CORE SUBSTRATE MARKET, BY SUBSTRATE SIZE

- 6.1 Up to 300 mm
- 6.2 300–510 mm
- 6.3 Above 510 mm

7 GLOBAL GLASS CORE SUBSTRATE MARKET, BY MANUFACTURING PROCESS

- 7.1 Through-Glass Via (TGV)
- 7.2 Laser Drilling
- 7.3 Wet Etching
- 7.4 Dry Etching
- 7.5 Metallization
- 7.6 Thin-Film Deposition

8 GLOBAL GLASS CORE SUBSTRATE MARKET, BY APPLICATION

- 8.1 AI Processors
- 8.2 High-Performance Computing (HPC)
- 8.3 Data Centers
- 8.4 Advanced Packaging
- 8.5 Memory Devices
- 8.6 RF & Photonics
- 8.7 Consumer Electronics
- 8.8 Automotive Electronics

9 GLOBAL GLASS CORE SUBSTRATE MARKET, BY END USER

- 9.1 Integrated Device Manufacturers (IDMs)
- 9.2 Foundries
- 9.3 OSAT Companies
- 9.4 Semiconductor Packaging Companies
- 9.5 Research Institutes & Universities

10 GLOBAL GLASS CORE SUBSTRATE MARKET, BY GEOGRAPHY

- 10.1 North America
 - 10.1.1 United States
 - 10.1.2 Canada
 - 10.1.3 Mexico
- 10.2 Europe
 - 10.2.1 United Kingdom
 - 10.2.2 Germany
 - 10.2.3 France
 - 10.2.4 Italy
 - 10.2.5 Spain
 - 10.2.6 Netherlands
 - 10.2.7 Belgium
 - 10.2.8 Sweden
 - 10.2.9 Switzerland
 - 10.2.10 Poland
 - 10.2.11 Rest of Europe
- 10.3 Asia Pacific
 - 10.3.1 China
 - 10.3.2 Japan
 - 10.3.3 India
 - 10.3.4 South Korea
 - 10.3.5 Australia
 - 10.3.6 Indonesia
 - 10.3.7 Thailand
 - 10.3.8 Malaysia
 - 10.3.9 Singapore
 - 10.3.10 Vietnam
 - 10.3.11 Rest of Asia Pacific
- 10.4 South America

- 10.4.1 Brazil
- 10.4.2 Argentina
- 10.4.3 Colombia
- 10.4.4 Chile
- 10.4.5 Peru
- 10.4.6 Rest of South America
- 10.5 Rest of the World (RoW)
 - 10.5.1 Middle East
 - 10.5.1.1 Saudi Arabia
 - 10.5.1.2 United Arab Emirates
 - 10.5.1.3 Qatar
 - 10.5.1.4 Israel
 - 10.5.1.5 Rest of Middle East
 - 10.5.2 Africa
 - 10.5.2.1 South Africa
 - 10.5.2.2 Egypt
 - 10.5.2.3 Morocco
 - 10.5.2.4 Rest of Africa

11 STRATEGIC MARKET INTELLIGENCE

- 11.1 Industry Value Network and Supply Chain Assessment
- 11.2 White-Space and Opportunity Mapping
- 11.3 Product Evolution and Market Life Cycle Analysis
- 11.4 Channel, Distributor, and Go-to-Market Assessment

12 INDUSTRY DEVELOPMENTS AND STRATEGIC INITIATIVES

- 12.1 Mergers and Acquisitions
- 12.2 Partnerships, Alliances, and Joint Ventures
- 12.3 New Product Launches and Certifications
- 12.4 Capacity Expansion and Investments
- 12.5 Other Strategic Initiatives

13 COMPANY PROFILES

- 13.1 Corning Incorporated
- 13.2 AGC Inc.
- 13.3 Schott AG

- 13.4 Samsung Electro-Mechanics Co., Ltd.
- 13.5 Absolics Inc.
- 13.6 LG Innotek Co., Ltd.
- 13.7 Intel Corporation
- 13.8 Ibiden Co., Ltd.
- 13.9 Shinko Electric Industries Co., Ltd.
- 13.10 TOPPAN Holdings Inc.
- 13.11 Kyocera Corporation
- 13.12 Unimicron Technology Corporation
- 13.13 Nan Ya Printed Circuit Board Corporation
- 13.14 Kinsus Interconnect Technology Corp.
- 13.15 Daeduck Electronics Co., Ltd.

List Of Tables

LIST OF TABLES

Table 1 Global Glass Core Substrate Market Outlook, By Region (2023-2034) (\$MN)

Table 2 Global Glass Core Substrate Market Outlook, By Glass Type (2023-2034) (\$MN)

Table 3 Global Glass Core Substrate Market Outlook, By Borosilicate Glass (2023-2034) (\$MN)

Table 4 Global Glass Core Substrate Market Outlook, By Fused Silica Glass (2023-2034) (\$MN)

Table 5 Global Glass Core Substrate Market Outlook, By Aluminosilicate Glass (2023-2034) (\$MN)

Table 6 Global Glass Core Substrate Market Outlook, By Quartz Glass (2023-2034) (\$MN)

Table 7 Global Glass Core Substrate Market Outlook, By Other Specialty Glasses (2023-2034) (\$MN)

Table 8 Global Glass Core Substrate Market Outlook, By Substrate Size (2023-2034) (\$MN)

Table 9 Global Glass Core Substrate Market Outlook, By Up to 300 mm (2023-2034) (\$MN)

Table 10 Global Glass Core Substrate Market Outlook, By 300–510 mm (2023-2034) (\$MN)

Table 11 Global Glass Core Substrate Market Outlook, By Above 510 mm (2023-2034) (\$MN)

Table 12 Global Glass Core Substrate Market Outlook, By Manufacturing Process (2023-2034) (\$MN)

Table 13 Global Glass Core Substrate Market Outlook, By Through-Glass Via (TGV) (2023-2034) (\$MN)

Table 14 Global Glass Core Substrate Market Outlook, By Laser Drilling (2023-2034) (\$MN)

Table 15 Global Glass Core Substrate Market Outlook, By Wet Etching (2023-2034) (\$MN)

Table 16 Global Glass Core Substrate Market Outlook, By Dry Etching (2023-2034) (\$MN)

Table 17 Global Glass Core Substrate Market Outlook, By Metallization (2023-2034) (\$MN)

Table 18 Global Glass Core Substrate Market Outlook, By Thin-Film Deposition (2023-2034) (\$MN)

Table 19 Global Glass Core Substrate Market Outlook, By Application (2023-2034) (\$MN)

Table 20 Global Glass Core Substrate Market Outlook, By AI Processors (2023-2034) (\$MN)

Table 21 Global Glass Core Substrate Market Outlook, By High-Performance Computing (HPC) (2023-2034) (\$MN)

Table 22 Global Glass Core Substrate Market Outlook, By Data Centers (2023-2034) (\$MN)

Table 23 Global Glass Core Substrate Market Outlook, By Advanced Packaging (2023-2034) (\$MN)

Table 24 Global Glass Core Substrate Market Outlook, By Memory Devices (2023-2034) (\$MN)

Table 25 Global Glass Core Substrate Market Outlook, By RF & Photonics (2023-2034) (\$MN)

Table 26 Global Glass Core Substrate Market Outlook, By Consumer Electronics (2023-2034) (\$MN)

Table 27 Global Glass Core Substrate Market Outlook, By Automotive Electronics (2023-2034) (\$MN)

Table 28 Global Glass Core Substrate Market Outlook, By End User (2023-2034) (\$MN)

Table 29 Global Glass Core Substrate Market Outlook, By Integrated Device Manufacturers (IDMs) (2023-2034) (\$MN)

Table 30 Global Glass Core Substrate Market Outlook, By Foundries (2023-2034) (\$MN)

Table 31 Global Glass Core Substrate Market Outlook, By OSAT Companies (2023-2034) (\$MN)

Table 32 Global Glass Core Substrate Market Outlook, By Semiconductor Packaging Companies (2023-2034) (\$MN)

Table 33 Global Glass Core Substrate Market Outlook, By Research Institutes & Universities (2023-2034) (\$MN)

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